BCC/MLF/MLP/LPCC



PRODUCT DESCRIPTION

Plastronics has taken a leadership role in designing and developing socket solutions for the newest QFN packages such as MLF, BCC and LPCC. These sockets offer a modular design in a small outline with very low inductance. The new Open Top QFN socket allows for more convenient package loading and unloading in most of the same lead count options as the lidded version.

SPECIFICATIONS (mm)

Available in .40, .50, .65, .80 and 1.00 mm pitches

Custom pitches down to .30 mm

Lidded and Open Top Sockets for ≤10 mm packages

Lidded Sockets for 10 - 16 mm packages

Center ground pin standard for all sockets

Optional copper heat slug available for high wattage devices Sockets for over 80 different JEDEC standard footprints

MECHANICAL PROPERTIES

· Mounting Method to Board

· Socket Operation

Operating Temperature

Contact Force

O O I I LUI C

· Life Cycles

Thru-hole Mount

Clamshell lid; ZIF Open Top

-50° C to +150° C

30 + -5 gf

5,000 Mechanical Cycles

PHYSICAL PROPERTIES

· Plastic Body

Contact Base Metal

Contact Plating

Center Pin Base Metal

Center Pin Plating

• Springs, Torsion/Coil

PPS

BeCu

Au over Ni; NiB optional

Brass; Cu optional

Au; NiB optional

Passivated S.S.

ELECTRICAL PROPERTIES

• Contact Resistance < 50 mOhms

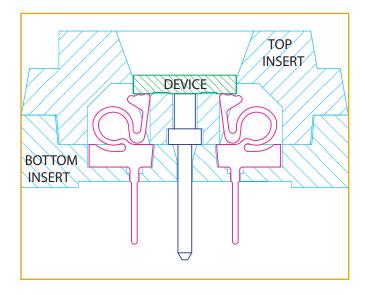
• Inductance 3 nH

• Current Rating .5A with 30°C rise, 1.0A with 75°C rise

• Volume Resistivity 1 x 10¹⁵ Ohm-cm

• Insulation Resistance 560 V/mil

CONTACT TECHNOLOGY



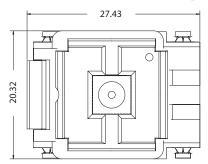


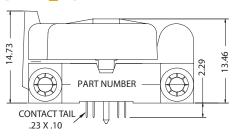
BCC/MLF/MLP/LPCC

QFN OFFERINGS

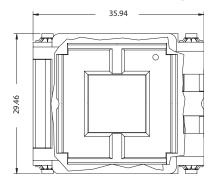
Plastronics offers over 140 QFN socket options. For a complete list, please visit our website at www.PlastronicsUSA.com.

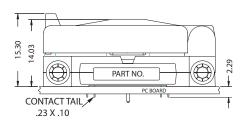
LIDDED BODY SIZE ≤10 mm



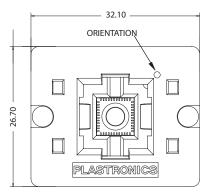


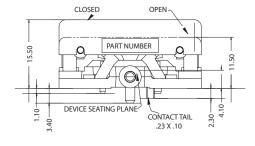
LIDDED BODY SIZE 10 - 16 mm





OPEN TOP BODY SIZE ≤10 mm





All units in mm unless otherwise noted.

PLASTRONICS

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